

February 2010

MCT6, MCT61, MCT62 Dual Phototransistor Optocouplers

Features

- Two isolated channels per package
- Two packages fit into a 16 lead DIP socket
- Choice of three current transfer ratios
- Underwriters Laboratory (U.L.) recognized File E90700
- VDE approved for IEC60747-5-2

Applications

- AC line/digital logic isolate high voltage transients
- Digital logic/digital logic eliminate spurious grounds
- Digital logic/AC triac control isolate high voltage transients
- Twisted pair line receiver eliminate ground loop feedthrough
- Telephone/telegraph line receiver isolate high voltage transients
- High frequency power supply feedback control maintain floating grounds and transients

Equivalent Circuit

- Relay contact monitor isolate floating grounds and transients
- Power supply monitor isolate transients

Description

The MCT6X Optocouplers have two channels for density applications. For four channel applications, two-packages fit into a standard 16-pin DIP socket. Each channel is an NPN silicon planar phototransistor optically coupled to a gallium arsenide infrared emitting diode.

ANODE 1 CATHODE 2 CATHODE 3 ANODE 4 EMITTER Package Outlines

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Rating	Value	Unit
TOTAL DEVICE			
T _{STG}	Storage Temperature	-55 to +150	°C
T _{OPR}	Operating Temperature	-55 to +100	°C
T _{SOL}	Lead Solder Temperature (Refer to Reflow Temperature Profile)	260 for 10 sec	°C
D	Total Device Power Dissipation @ T _A = 25°C	400	mW
P_{D}	Derate above 25°C	5.33	mW/°C
EMITTER (Each	channel)		
I _F	Forward Current – Continuous	60	mA
I _F (pk)	Forward Current – Peak (PW = 1µs, 300pps)	3	А
V _R	Reverse Voltage	3.0	V
В	LED Power Dissipation @ T _A = 25°C	100	mW
P_{D}	Derate above 25°C (Total Input)	1.3	mW/°C
DETECTOR (Ea	ch channel)		
I _C	Collector Current – Continuous	30	mA
P_{D}	Detector Power Dissipation @ T _A = 25°C	150	mW
	Derate above 25°C	2.0	mW/°C

Electrical Characteristics (T_A = 25°C unless otherwise specified)

Individual Component Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.*	Max.	Units
EMITTER			•			
V _F	Input Forward Voltage	I _F = 20mA		1.2	1.5	V
V _R	Reverse Voltage	I _R = 10μA	3.0	25		V
I _R	Reverse Current	$V_R = 5V$		0.001	10	μA
CJ	Junction Capacitance	$V_F = 0V, f = 1MHz$		50		pF
DETECTO	PR		•			
BV _{CEO}	Collector-Emitter Breakdown Voltage	$I_C = 1.0 \text{mA}, I_F = 0$	30	85		V
BV _{ECO}	Emitter-Collector Breakdown Voltage	$I_E = 100 \mu A, I_F = 0$	6	13		V
I _{CEO}	Collector-Emitter Dark Current	$V_{CE} = 10V, I_F = 0$		5	100	nA
C _{CE}	Capacitance	$V_{CE} = 0V, f = 1MHz$		8		pF

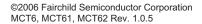
Transfer Characteristics

Symbol	Characteristic	Test Conditions	Min.	Тур.*	Max.	Units
SWITCHIN	SWITCHING CHARACTERISTICS (AC)					
t _{on}	Non-Saturated Turn-on Time	$R_L = 100\Omega, I_C = 2mA, V_{CC} = 10V$		2.4		μs
t _{off}	Non-Saturated Turn-off Time			2.4		μs
CURRENT TRANSFER RATIO, COLLECTOR-EMITTER (DC)						
CTR	MCT6	$I_F = 10 \text{mA}, V_{CE} = 10 \text{V}$	20			%
	MCT61	$I_F = 5mA$, $V_{CE} = 5V$	50			
	MCT62		100			
V _{CE(sat)}	Saturation Voltage	I _F = 16mA, I _C = 2mA		0.15	0.40	V

Isolation Characteristics

Symbol	Characteristic	Test Conditions	Min.	Тур.*	Max.	Units
V _{ISO}	Input-Output Isolation Voltage	$I_{I-O} \le 10\mu A$, $t = 1min$.	5000			Vac(rms)
R _{ISO}	Isolation Resistance	V _{I-O} = 500VDC	10 ¹¹			Ω
C _{ISO}	Isolation Capacitance	f = 1MHz		0.5		pF

^{*}All typicals at T_A = 25°C



Typical Performance Curves

Fig. 1 Normalized CTR vs. Forward Current

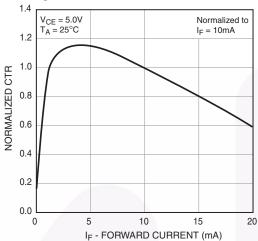


Fig. 2 Normalized CTR vs. Ambient Temperature

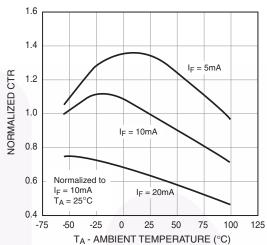


Fig. 3 Dark Current vs. Ambient Temperature

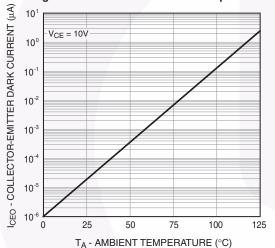


Fig. 4 Switching Speed vs. Load Resistor

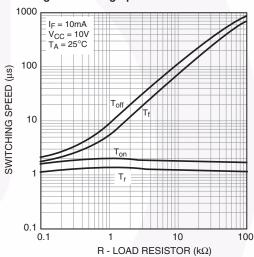


Fig. 5 LED Forward Voltage vs. Forward Current

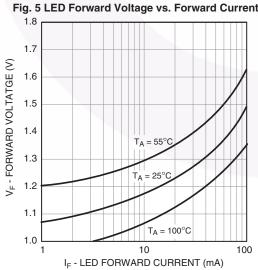
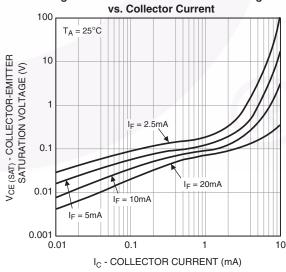
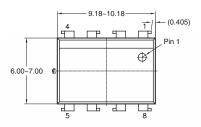


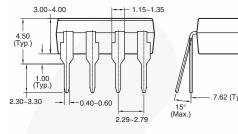
Fig. 6 Collector-Emitter Saturation Voltage



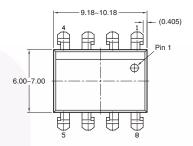
Package Dimensions

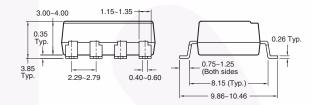
Through Hole



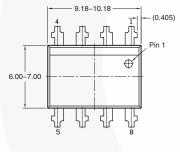


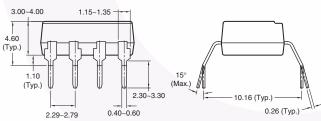
Surface Mount



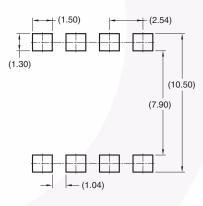


0.4" Lead Spacing





Recommend Pad Layout for Surface Mount Leadform



Note:

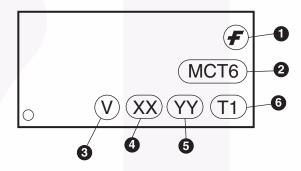
All dimensions are in millimeters.

0.26 (Typ.)

Ordering Information

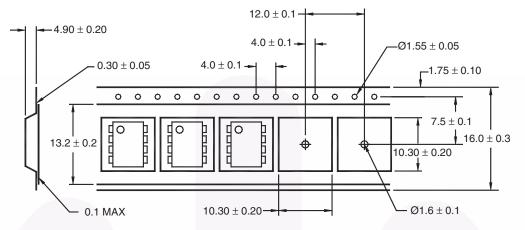
Option Example Part Number		Description
No Option	MTC6	Standard Through Hole
S MTC6S Surface Mount Lead Bend		Surface Mount Lead Bend
SD MTC6SD Surface Mount; Tape and Reel		Surface Mount; Tape and Reel
300	MCT6300	VDE Approved
3S	MCT63S	Surface Mount Lead Bend; VDE Approved
3SD	MCT63SD	Surface Mount; Tape and Reel; VDE Approved
300W	MTC6300W	0.4" Lead Spacing; VDE Approved

Marking Information



Definiti	ons	
1	Fairchild logo	
2	Device number	
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)	
4	Two digit year code, e.g., '03'	
5	Two digit work week ranging from '01' to '53'	
6	Assembly package code	

Carrier Tape Specifications

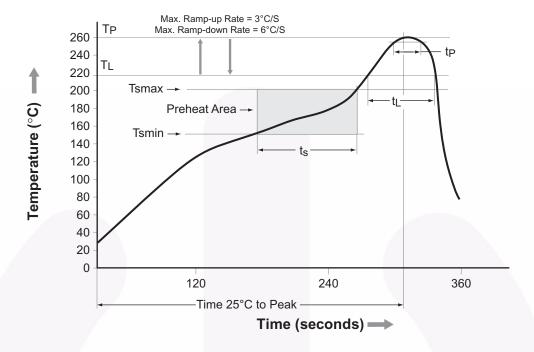


User Direction of Feed ----

Note:

All dimensions are in inches (millimeters)

Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (t _S) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60-150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.





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Definition of Terms				
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